

Series L5 / Ø 5mm

Colour: blue

Sloan Part No.: L5-B91G-WUV

Electrical and Optical Characteristics (T_A = 25°C)

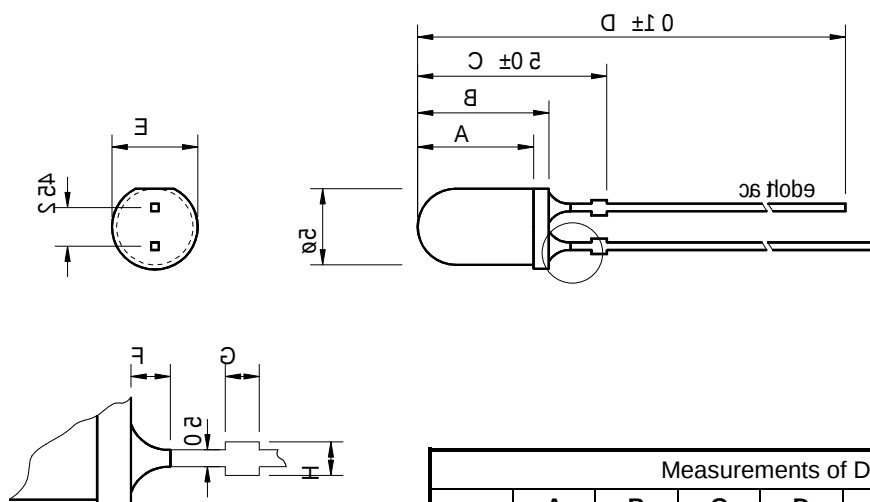
Chip			Lens	Absolute Maximum Ratings				Electro-Optical-Data's at 20mA					Viewing Angle 2 θ ½ (deg)
Emitted Colour	Peak Wavelength λ _p (nm)	Dominant Wavelength λ _p (nm)		Δλ (nm)	Pd (mW)	If (mA)	Peak If (mA)	Forward Voltage Vf (V)		Luminous Intensity Iv (mcd)			
								typ.	max	min.	typ.	max.	
Blue	470	470	water clear	-	123	35	110	3.2	3.5	4880	7300	9750	15°

*Peak Forward Current (1/10 Duty Cycle, 10μs Pulse Width)

Absolute Maximum Ratings (T_A = 25°C)

Reverse Voltage	5V
Reverse Current (V _R = 5V)	≤50μA
Operating Temperature Range	- 30°C ~ +85°C
Storage Temperature Range	- 40°C ~ +100°C
Lead Soldering Temperature (3mm below the body)	265°C for 10 seconds

Package Dimensions



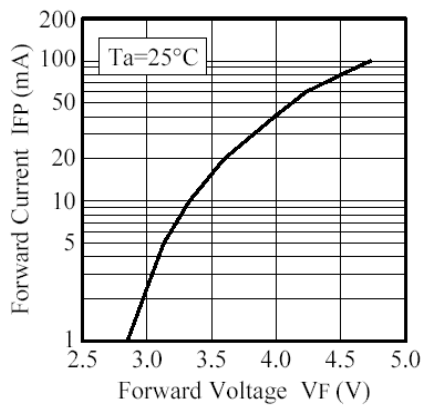
Measurements of Drawing								
	A	B	C	D	E	F	G	H
mm	7.6	8.6	12.4	28.9	5.6	1.5	1.0	1.1

1. All dimensions are in millimetres.
2. Tolerance is ±0.25mm unless otherwise specified.
3. Lead spacing is measured where the leads emerge from the package
4. Specifications are subject to change without notice.

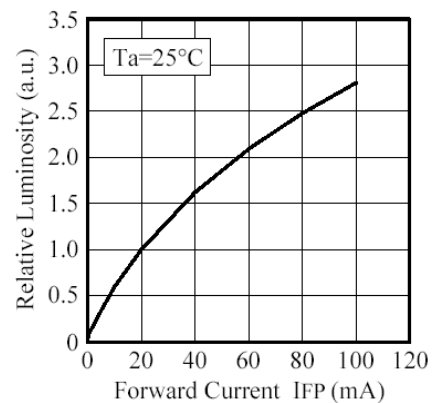
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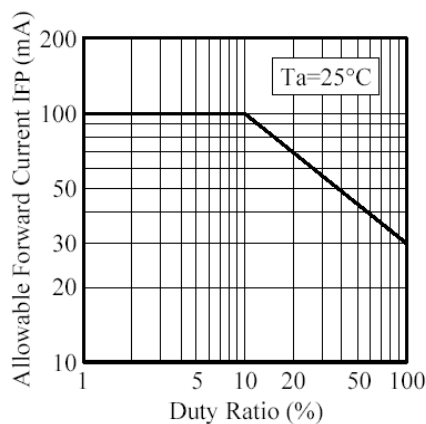
Forward Voltage vs. Forward Current



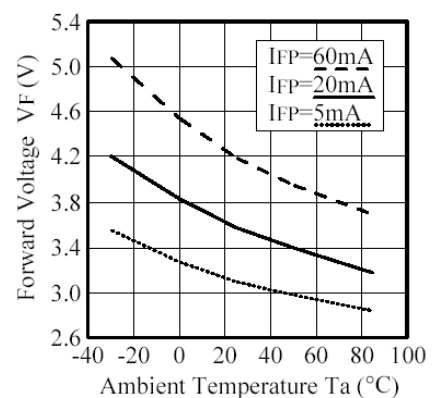
Forward Current vs. Relative Luminosity



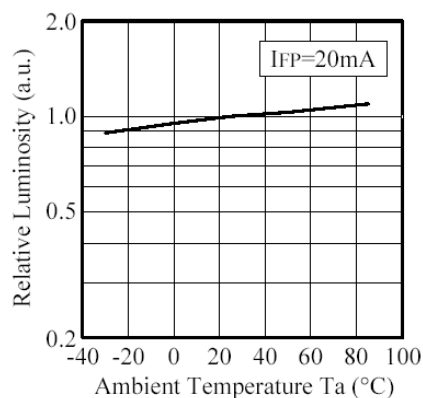
Duty Ratio vs. Allowable Forward Current



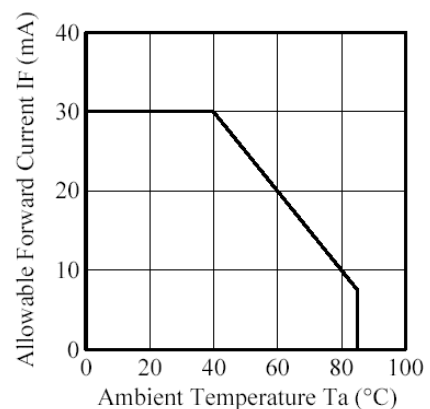
Ambient Temperature vs. Forward Voltage



Ambient Temperature vs. Relative Luminosity



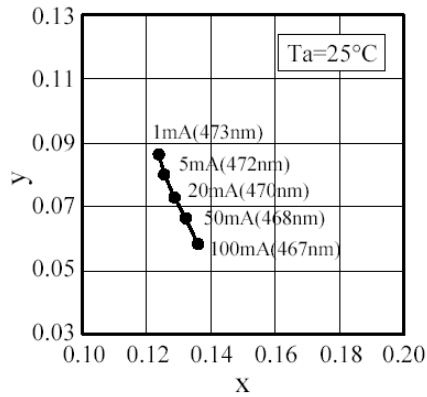
Ambient Temperature vs. Allowable Forward Current



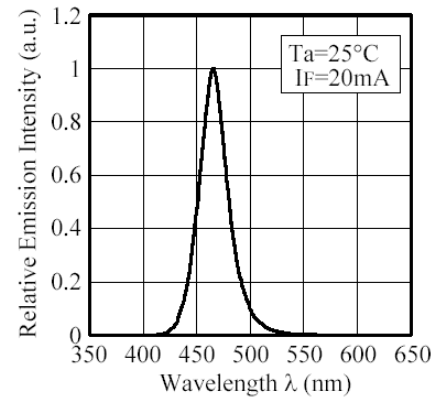
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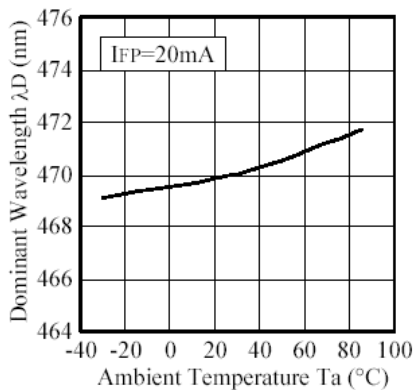
Forward Current vs. Chromaticity Coordinate



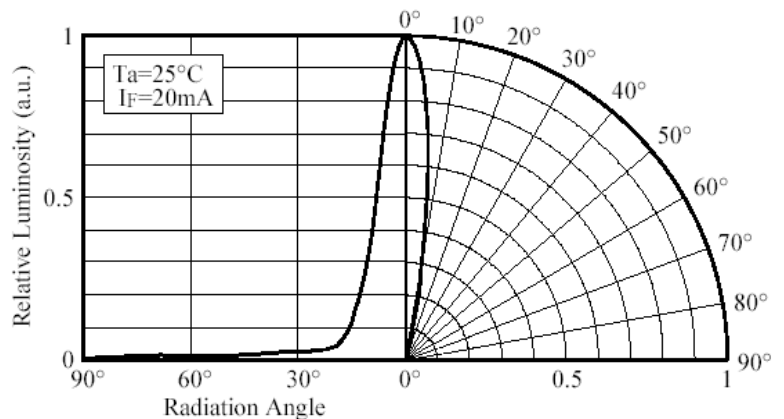
Spectrum



Ambient Temperature vs. Dominant Wavelength



Directivity



Recommended Soldering Conditions:

Dip Soldering		Hand Soldering	
Pre-Heat	120°C Max.	Temperature	350°C Max.
Pre-Heat Time	60 seconds Max.	Soldering Time	3 seconds Max.
Solder Bath	260°C Max.	Position	No closer than 3 mm from the base of the epoxy bulb.
Temperature			
Dipping Time	10 seconds Max.		
Dipping Position	No lower than 3 mm from the base of the epoxy bulb.		